Preferred Device

General Purpose Transistor

NPN Silicon

These transistors are designed for general purpose amplifier applications. They are housed in the SOT-416/SC-75 package which is designed for low power surface mount applications.

Features

• Pb–Free Package is Available

MAXIMUM RATINGS ($T_A = 25^{\circ}C$)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	40	Vdc
Collector-Base Voltage	V _{CBO}	75	Vdc
Emitter-Base Voltage	V _{EBO}	6.0	Vdc
Collector Current – Continuous	۱ _C	600	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation (Note 1) $T_A = 25^{\circ}C$	PD	150	mW
Thermal Resistance, Junction-to-Ambient	R_{\thetaJA}	833	°C/W
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to +150	°C

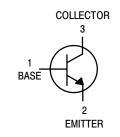
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

 Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.



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MARKING DIAGRAM



1P = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT2222ATT1	SOT-416	3000 / Tape & Reel
MMBT2222ATT1G	SOT-416 (Pb-Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

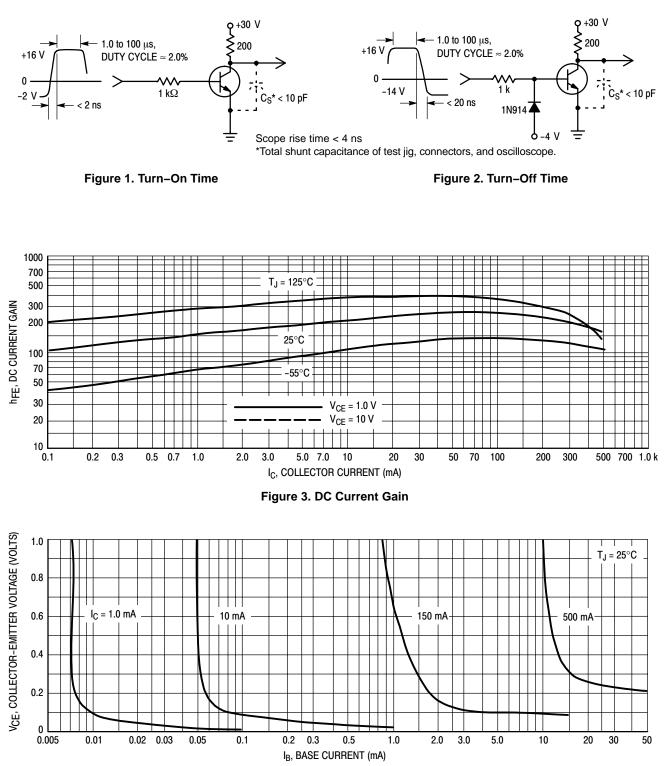
ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Chara	cteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (N $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	ote 1)	V _{(BR)CEO}	40	-	Vdc
Collector-Base Breakdown Voltage $(I_C = 10 \ \mu Adc, I_E = 0)$	V _{(BR)CBO}	75	-	Vdc	
Emitter – Base Breakdown Voltage $(I_E = 10 \ \mu Adc, I_C = 0)$		V _{(BR)EBO}	6.0	-	Vdc
Base Cutoff Current (V _{CE} = 60 Vdc, V _{EB} = 3.0 Vdc)		I _{BL}	-	20	nAdc
Collector Cutoff Current (V _{CE} = 60 Vdc, V _{EB} = 3.0 Vdc)	ICEX	-	10	nAdc	
ON CHARACTERISTICS (Note 2)					1
		H _{FE}	35 50 75 100 40	- - - -	_
$\begin{array}{l} \mbox{Collector}-\mbox{Emitter Saturation Voltage} \\ (I_{C}=150\mbox{ mAdc},\ I_{B}=15\mbox{ mAdc}) \\ (I_{C}=500\mbox{ mAdc},\ I_{B}=50\mbox{ mAdc}) \end{array}$		V _{CE(sat)}	- -	0.3 1.0	Vdc
Base – Emitter Saturation Voltage ($I_C = 150 \text{ mAdc}, I_B = 15 \text{ mAdc}$) ($I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc}$)		V _{BE(sat)}	0.6	1.2 2.0	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Current-Gain – Bandwidth Product ($I_C = 20$ mAdc, $V_{CE} = 20$ Vdc, f = 100	MHz)	f _T	300	-	MHz
Output Capacitance (V_{CB} = 10 Vdc, I_E = 0, f = 1.0 MHz)		C _{obo}	-	8.0	pF
Input Capacitance $(V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$		C _{ibo}	-	30	pF
Input Impedance $(V_{CE} = 10 \text{ Vdc}, I_C = 10 \text{ mAdc}, f = 1.0 \text{ k}$	Hz)	h _{ie}	0.25	1.25	kΩ
Voltage Feedback Ratio ($V_{CE} = 10 \text{ Vdc}, I_C = 10 \text{ mAdc}, f = 1.0 \text{ kHz}$)		h _{re}	-	4.0	X 10 ⁻⁴
Small – Signal Current Gain (V _{CE} = 10 Vdc, I _C = 10 mAdc, f = 1.0 k	Hz)	h _{fe}	75	375	-
Output Admittance ($V_{CE} = 10 \text{ Vdc}, I_C = 10 \text{ mAdc}, f = 1.0 \text{ kHz}$)		h _{oe}	25	200	μmhos
Noise Figure (V _{CE} = 10 Vdc, I _C = 100 μAdc, R _S = 1.0 k ohms, f = 1.0 kHz)		NF	-	4.0	dB
SWITCHING CHARACTERISTICS				•	
Delay Time	$(V_{CC} = 3.0 \text{ Vdc}, V_{BE} = -0.5 \text{ Vdc}.$	t _d	_	10	

Delay Time	$(V_{CC} = 3.0 \text{ Vdc}, V_{BE} = -0.5 \text{ Vdc},$	t _d	-	10	20	
Rise Time	$I_{C} = 150 \text{ mAdc}, I_{B1} = 15 \text{ mAdc})$	t _r	-	25	ns	
Storage Time	$(V_{CC} = 30 \text{ Vdc}, I_{C} = 150 \text{ mAdc},$	t _s	-	225	ns	
Fall Time	$I_{B1} = I_{B2} = 15 \text{ mAdc}$)	t _f	-	60	115	

Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.
Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

SWITCHING TIME EQUIVALENT TEST CIRCUITS





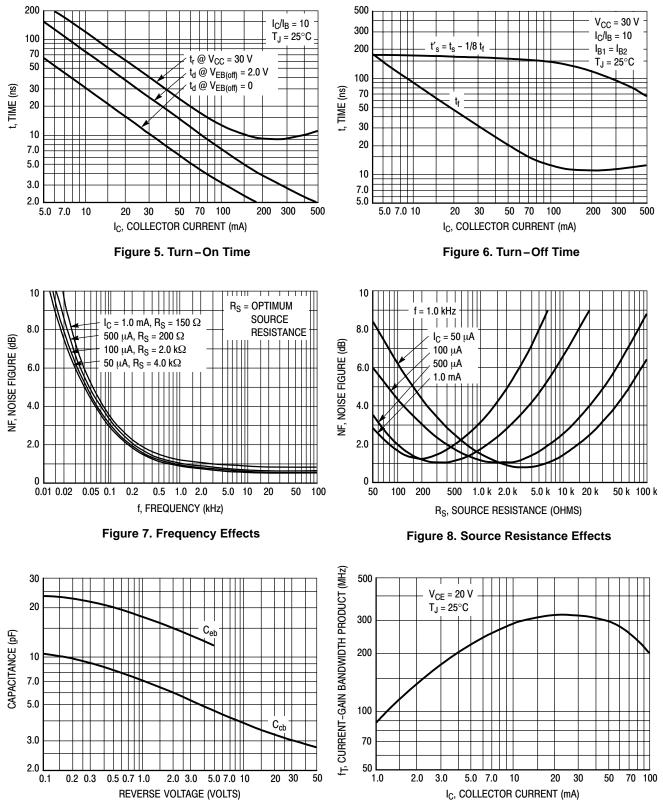


Figure 9. Capacitances

Figure 10. Current–Gain Bandwidth Product

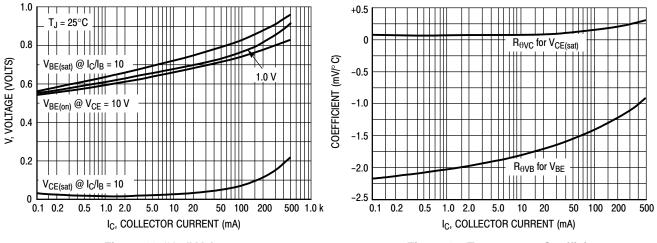
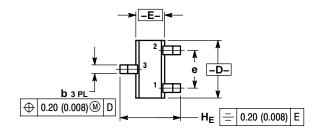


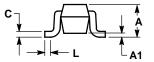
Figure 11. "On" Voltages

Figure 12. Temperature Coefficients

PACKAGE DIMENSIONS

SC-75/SOT-416 CASE 463-01 **ISSUE F**





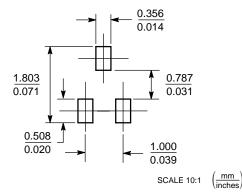
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.70	0.80	0.90	0.027	0.031	0.035	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
b	0.15	0.20	0.30	0.006	0.008	0.012	
С	0.10	0.15	0.25	0.004	0.006	0.010	
D	1.55	1.60	1.65	0.059	0.063	0.067	
Ε	0.70	0.80	0.90	0.027	0.031	0.035	
е	1	.00 BSC)	0.04 BSC			
L	0.10	0.15	0.20	0.004	0.006	0.008	
HE	1.50	1.60	1.70	0.061	0.063	0.065	

STYLE 1: PIN 1. BASE

2. EMITTER 3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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